

08-12-2002

FORM PTO-1595
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)
M&G- 10873.1011US01

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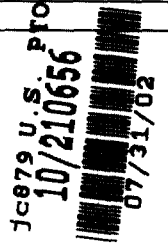
Koji Makita
Hideto Adachi
Toshiya Kawata
Hiroshi Asaka
Osamu Imafuji

Toshiya Fukuhisa
Akira Takamori

7.31.02

2. Name and address of receiving party(ies):

Matsushita Electric Industrial Co., Ltd.
1006-banchi Oaza-Kadoma
Kadoma-shi
Osaka 571-8501
Japan



Additional name(s) of conveying party(ies) attached? Yes No

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Execution Date: July 18, 2002

4. Application number(s) or patent number(s):

10/210656

If this document is being filed together with a new application, the execution date of the application is: July 18, 2002

A. Patent Application No.(s)

B. Patent No.(s)

Filed herewith

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Douglas P. Mueller
Address: Merchant & Gould P.C.
P.O. Box 2903
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6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

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08/09/2002 TBIAZ1 00000028 10210656
01 FC:581 40.00 OP

PATENT
REEL: 13166 FRAME: 0664

WHEREAS,

Inventor(s) Name,
Address, Citizenship

1. Koji MAKITA residing at 1220-13-B202, Shioya, Akou-shi, Hyogo 678-0201, JAPAN and a citizen of JAPAN;
2. Hideto ADACHI residing at 338-B102, Higashikawara, Okayama-shi, Okayama 703-8255, JAPAN and a citizen of JAPAN;
3. Toshiya KAWATA residing at A-201, Sharumantatsunokuchi, 144-7, Shinogoze, Okayama-shi, Okayama 703-8201, JAPAN and a citizen of JAPAN;
4. Hiroshi ASAKA residing at 20-14, Okurahigashimachi, Hirakata-shi, Osaka 573-1174, JAPAN and a citizen of JAPAN;
5. Osamu IMAFUJI residing at 10-5-507, Kamihamuro 1-chome, Takatsuki-shi, Osaka 569-1044, JAPAN and a citizen of JAPAN;
6. Toshiya FUKUHISA residing at 4-7-36, Amamiminami, Matsubara-shi, Osaka 580-0033, JAPAN and a citizen of JAPAN;
7. Akira TAKAMORI residing at 35-1-406, Yamadahigashi 4-chome, Suita-shi, Osaka 565-0821, JAPAN and a citizen of JAPAN;

Date Patent Declaration
Signed and Title Serial
No. and filing date (if
known)

(herein called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States on for this invention, which application is entitled

SEMICONDUCTOR LASER AND METHOD FOR MANUFACTURING THE SAME

and which has been given Serial Number _____ and the filing date of _____;

Name of Corporation

AND WHEREAS Matsushita Electric Industrial Co., Ltd. (herein called "ASSIGNEE"), a corporation organized under the laws of JAPAN, and having an office and place of business at 1006-banchi, Oaza-Kadoma, Kadoma-shi, Osaka 571-8501, JAPANState or Country of
Incorporation and Address

wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign and transfer to the ASSIGNEE, its successors and assigns, the entire right, title and interest for the United States in and to the invention disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents to issue any and all United States Letters Patent for the aforesaid invention to the ASSIGNEE of the entire right, title and interest in and to the same, for the use of the ASSIGNEE, its successors and assigns.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to THE UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns the entire right, title and interest in and to the said invention, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE its successors and assigns, that no assignment grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by THE UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by THE UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Each inventor must sign & date

Note: No legalization or other witness required

<u>Koji Makita</u> Signature	<u>July 18, 2002</u> Date
<u>Hideito Adachi</u> Signature	<u>July 18, 2002</u> Date
<u>Toshiya Kanata</u> Signature	<u>July 18, 2002</u> Date
<u>Kiroshi Aaka</u> Signature	<u>July 18, 2002</u> Date
<u>Osamu Inafuji</u> Signature	<u>July 18, 2002</u> Date
<u>Yoshiya Fukuhisa</u> Signature	<u>July 18, 2002</u> Date
<u>Akira Takamori</u> Signature	<u>July 18, 2002</u> Date